HALOGEN

FREE

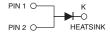


## Vishay General Semiconductor

# High Current Density Surface Mount Trench MOS Barrier Schottky Rectifier

Ultra Low  $V_F = 0.42 \text{ V}$  at  $I_F = 5 \text{ A}$ 

# TMBS® eSMP® Series



**SlimDPAK** 

PRIMARY CHARACTERISTICS			
I <sub>F(AV)</sub>	35 A		
V <sub>RRM</sub>	120 V		
I <sub>FSM</sub>	260 A		
V <sub>F</sub> at I <sub>F</sub> = 35 A (T <sub>A</sub> = 125 °C)	0.68 V		
T <sub>J</sub> max.	175 °C		
Package	SlimDPAK		
Diode variation	Single die		

#### **FEATURES**

- Very low profile typical height of 1.3 mm
- Trench MOS Schottky technology
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### TYPICAL APPLICATIONS

For use in low voltage high frequency DC/DC converters, freewheeling diodes, and polarity protection applications.

#### **MECHANICAL DATA**

Case: SlimDPAK

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V35PWM12	UNIT	
Device marking code		V35PWM12		
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	120	V	
Maximum average forward rectified current (Fig. 1)	I <sub>F(AV)</sub> (1)	35	А	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	I <sub>FSM</sub> 260		
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	-40 to +175	°C	

#### Note

(1) With infinite heat sink



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Maximum Instantaneous forward voltage	$I_F = 5.0 \text{ A}$	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.51	-	V
	I <sub>F</sub> = 17.5 A			0.72	-	
	I <sub>F</sub> = 35 A			0.96	1.05	
	$I_F = 5.0 \text{ A}$	T <sub>A</sub> = 125 °C		0.42	-	
	I <sub>F</sub> = 17.5 A			0.59	-	
	$I_F = 35 A$			0.68	0.76	
Reverse current	$V_{R} = 90 \text{ V}$	T <sub>A</sub> = 25 °C	I <sub>R</sub> (2)	0.01	-	mA
	v <sub>R</sub> = 90 v	T <sub>A</sub> = 125 °C		7	-	
	V <sub>R</sub> = 120 V	T <sub>A</sub> = 25 °C		i	1.2	
		T <sub>A</sub> = 125 °C		13	40	
Typical junction capacitance	4.0 V, 1 MHz		CJ	2080	-	pF

#### Notes

 $^{(1)}\,$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

(2) Pulse test: pulse width  $\leq 5$  ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	TER SYMBOL V35PWM12			
Tunical thormal registance	R <sub>θJA</sub> (1)(2)	55	°C/W	
Typical thermal resistance	R <sub>0JM</sub> (3)	1.5		

#### Notes

- $^{(1)}$  The heat generated must be less than thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$
- $^{(2)}$  Free air, mounted on recommended copper pad area; thermal resistance  $R_{\theta JA}$  junction to ambient
- $^{(3)}$  Mounted on infinite heat sink; thermal resistance  $R_{\theta JM}$  junction-to-mount

ORDERING INFORMATION (Example)					
PREFERRED P/N UNIT WEIGHT (g) PREFERRED PACKAGE CODE		BASE QUANTITY	DELIVERY MODE		
V35PWM12-M3/I	0.20	1	4500	13" diameter plastic tape and reel	
V35PWM12HM3/I (1)	0.20	I	4500	13" diameter plastic tape and reel	

#### Note

(1) AEC-Q101 qualified

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## **RATINGS AND CHARACTERISTICS CURVES** (T<sub>A</sub> = 25 °C unless otherwise noted)

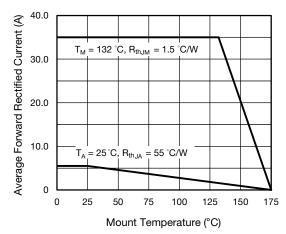


Fig. 1 - Maximum Forward Current Derating Curve

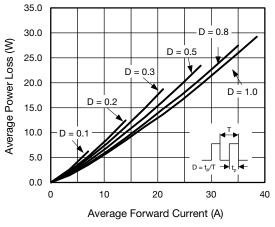


Fig. 2 - Forward Power Loss Characteristics

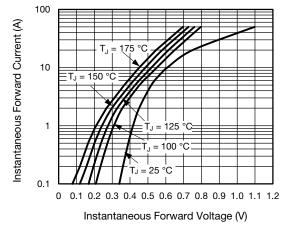


Fig. 3 - Typical Instantaneous Forward Characteristics

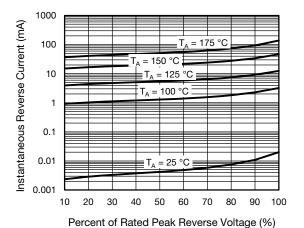


Fig. 4 - Typical Reverse Leakage Characteristics

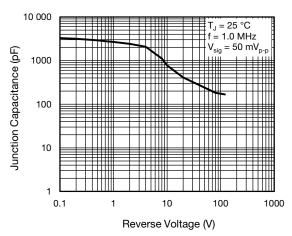


Fig. 5 - Typical Junction Capacitance

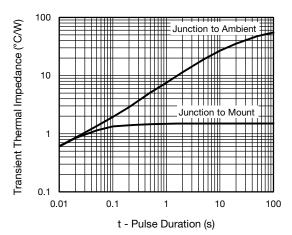


Fig. 6 - Typical Transient Thermal Impedance



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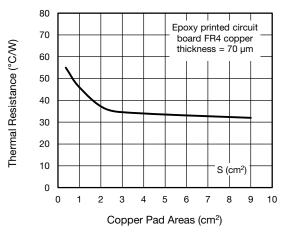
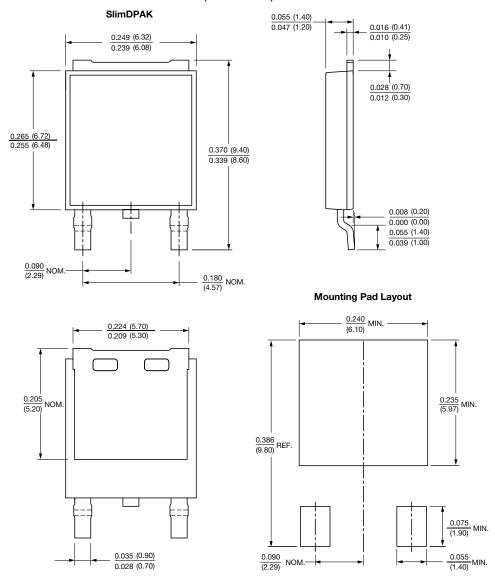


Fig. 7 - Typical Resistance Junction to Ambient vs. Copper Pad Areas

#### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)





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